Claims

1. Method for mounting a switching module, in which a circuit support (1, 42) is inserted into the basic housing element (10, 35, 44) with its flat sides (63, 64) facing walls (20, 21, 46, 53) of a basic housing element (10, 35, 44) and the basic housing element (10, 35, 44) is closed with the aid of cover elements (6, 25, 37, 47, 52),
characterized in that
a longitudinally extended pressure strip (26, 49) is inserted between the circuit support (1, 42) and the basic housing element (10, 35, 44), by means of which a compression force acting on a flat side (64) of the circuit support (1, 42) is applied and that the pressure strip (26, 49) is guided by guide means (17, 18, 19, 50) configured on the inside of the basic housing element (10, 44).

2. Method according to Claim 1,
characterized in that the pressure strip (26, 49) configured as a tension spring is charged during insertion of the circuit support (1, 42) and released to fix the circuit support (1, 42) in the basic housing element (10, 44).

3. Method according to Claim 1,
characterized in that the pressure strip (26, 49) configured as a compression spring for fixing the printed circuit board (1, 42) is subject to a pressure (57) that compresses the compression spring.

4. Method according to Claim 3,
characterized in that the pressure (57) is applied by the cover elements (47, 52) of the basic housing element (44)

5. Method according to one of Claims 1 to 4, characterized in that the pressure strip (26, 49) is guided inside the basic housing element (10, 44) by an encapsulated guide groove (17, 50).

6. Method according to one of Claims 1 to 5, characterized in that the circuit support (1, 42) is guided by guide elements (16, 18, 19, 36, 45) during insertion into the basic housing element (10, 35, 44).

7. Method according to Claim 6, characterized in that the circuit support (1, 42) is fitted with components on both sides before insertion into the basic housing element (10, 35, 44).

8. Method according to one of Claims 1 to 7, characterized in that a cover element (6, 47) is fixed to the circuit support (1, 42) before insertion of the circuit support (1, 42) into the basic housing element (10, 35, 44).

9. Method according to Claim 8, characterized in that contact means (5, 7, 48) configured on the cover element (6, 47) are connected to the circuit support (1, 42) before insertion of the circuit support (1, 42) into the basic housing element (10, 35, 44).

10. Method according to one of Claims 1 to 9, characterized in that the pressure strip (26, 49) is inserted into the basic housing element (10, 35, 44) together with the circuit support (1, 42)).

11. Method according to one of Claims 1 to 10, characterized in that a cover element (25, 47) provided with the pressure strip (26, 49) is attached to an opening (15, 43) in the basic housing element (10, 35, 44).

12. Method according to one of Claims 1 to 11, characterized in that the pressure strip (26) is tailored to the length of the basic housing element (10) at breaking points (34) before insertion into the basic housing element (10).

13. Method according to one of Claims 1 to 12, characterized in that the pressure strip (26) is held positively in a recess (33) in an opposite cover element (6).

14. Method according to one of Claims 1 to 13, characterized in that a saw-tooth profile (32) is configured on the pressure strip (26) and is held positively in latch points on the recess (33).

15. Method according to Claim 13 or 14, characterized in that the basic housing element (10, 35) is clamped between opposite cover elements (6, 25, 37).

16. Method according to one of Claims 1 to 15, characterized in that a cover element (37) is fixed to the circuit support (1) by way of clamping means (39, 40) during attachment of a cover element (37) to an opening (15) in the

basic housing element (35).

17. Method according to one of Claims 1 to 16, characterized in that the openings (12, 15) on the transverse sides (11, 14) of the basic housing element (10, 35) are sealed by means of identical seals (24, 30).

18. Switching module with an electronic component arranged inside a housing, characterized in that the switching module can be produced using a method according to at least one of Claims 1 to 17.